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Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild <a href="general-regarding-numbers-n

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FDS86240

N-Channel Shielded Gate PowerTrench® MOSFET 150 V, 7.5 A, 19.8 m Ω

Features

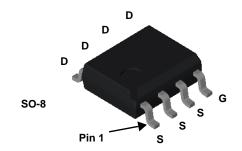
- Shielded Gate MOSFET Technology
- Max $r_{DS(on)} = 19.8 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 7.5 \text{ A}$
- Max $r_{DS(on)}$ = 26 m Ω at V_{GS} = 6 V, I_D = 6.4 A
- High Performance Trench Technology for Extremely Low r_{DS(on)}
- High Power and Current Handling Capability in a Widely Used Surface Mount Package
- 100% UIL Tested
- RoHS Compliant

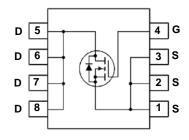
General Description

This N-Channel MOSFET is produced using ON Semiconductor's advanced PowerTrench® process that incorporates Shielded Gate technology. This process has been optimized for $r_{DS(on)}$, switching performance and ruggedness.

Applications

- DC/DC Converters and Off-Line UPS
- Distributed Power Architectures and VRMs
- Primary Switch for 24 V and 48 V Systems
- High Voltage Synchronous Rectifier





MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted.

Symbol	Parar	meter		Ratings	Units
V _{DS}	Drain to Source Voltage			150	V
V_{GS}	Gate to Source Voltage			±20	V
I _D	Drain Current -Continuous			7.5	А
	-Pulsed		(Note 4)	199	
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	220	mJ
P_{D}	Power Dissipation	T _C = 25 °C	(Note 1)	5.0	W
	Power Dissipation	T _A = 25 °C	(Note 1a)	2.5	VV
T _J , T _{STG}	Operating and Storage Junction Tempe	rature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	25	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	50	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS86240	FDS86240	SO-8	13 "	12 mm	2500 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted.

Symbol	Parameter Test Conditions		Min.	Тур.	Max.	Units
Off Chara	acteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	150			V
$\frac{\Delta BV_{DS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		105		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 120 V, V _{GS} = 0 V			1	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2	2.7	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		-11		mV/°C
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 7.5 \text{ A}$		17.3	19.8	
		$V_{GS} = 6 \text{ V}, I_D = 6.4 \text{ A}$		19.7	26	mΩ
		$V_{GS} = 10 \text{ V}, I_D = 7.5 \text{ A}, T_J = 125 \text{ °C}$		30.8	35.3	
9 _{FS}	Forward Transconductance	$V_{DS} = 10 \text{ V}, I_{D} = 7.5 \text{ A}$		26		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 75 V V 0 V	1930	2570	pF
C _{oss}	Output Capacitance	$V_{DS} = 75 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$	198	265	pF
C _{rss}	Reverse Transfer Capacitance	1 – 1 1911 12	8.3	15	pF
R_g	Gate Resistance		0.84		Ω

Switching Characteristics

	•					
t _{d(on)}	Turn-On Delay Time			14	26	ns
t _r	Rise Time	V _{DD} = 75 V, I _D = 7.5 A,		4.2	10	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = 10 V, R _{GEN}	= 6 Ω	24	39	ns
t _f	Fall Time			4.9	10	ns
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to } 10 \text{ V}$		28	40	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to 5 V}$	V _{DD} = 75 V,	16	22	nC
Q_{gs}	Gate to Source Charge		I _D = 7.5 A	7.6		nC
Q_{gd}	Gate to Drain "Miller" Charge			5.3		nC

Drain-Source Diode Characteristics

V _{SD}	Source to Drain Dioge Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 7.5 \text{ A}$	(Note 2)	0.77	1.3	\/
		$V_{GS} = 0 \text{ V}, I_{S} = 2 \text{ A}$	(Note 2)	0.70	1.2	
t _{rr}	Reverse Recovery Time	I _F = 7.5 A, di/dt = 100 A/μs		75	120	ns
Q _{rr}	Reverse Recovery Charge	-1 F = 7.5 A, αι/αι = 100 A/μs		109	175	nC

NOTES

^{1.} R_{0JA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0JC} is guaranteed by design while R_{0CA} is determined by the user's board design.



a) 50 °C/W when mounted on a 1 in² pad of 2 oz copper.



b) 125 °C/W when mounted on a minimum pad.

- 2. Pulse Test: Pulse Width < 300 $\mu\text{s},$ Duty cycle < 2.0%.
- 3. Starting $T_J = 25~^{\circ}C,~L = 1~mH,~I_{AS} = 21~A,~V_{DD} = 135~V,~V_{GS} = 10~V.$
- 4. Pulsed Id please refer to Fig 11 SOA graph for more details.

Typical Characteristics $T_J = 25$ °C unless otherwise noted.

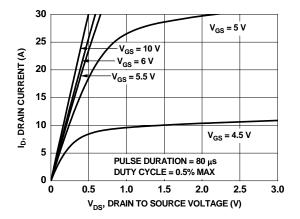


Figure 1. On Region Characteristics

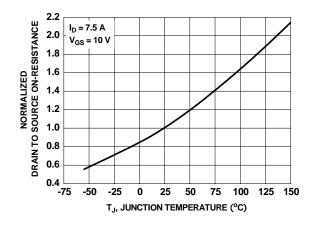


Figure 3. Normalized On Resistance vs. Junction Temperature

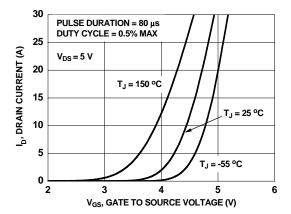


Figure 5. Transfer Characteristics

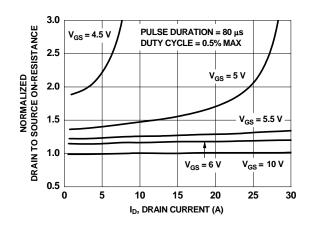


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

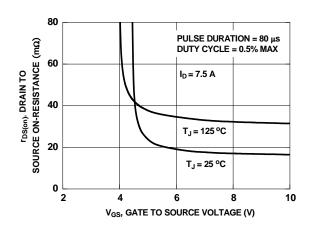


Figure 4. On-Resistance vs. Gate to Source Voltage

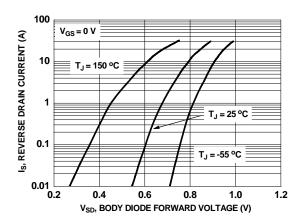


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

Typical Characteristics T_J = 25 °C unless otherwise noted.

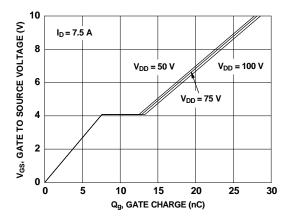


Figure 7. Gate Charge Characteristics

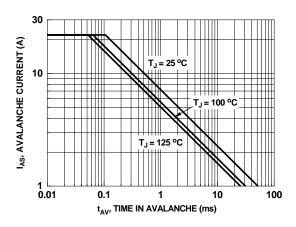


Figure 9. Unclamped Inductive Switching Capability

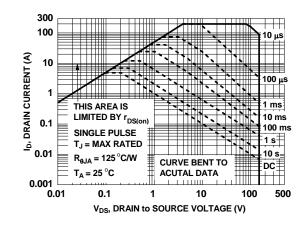


Figure 11. Forward Bias Safe Operating Area

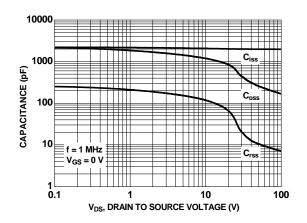


Figure 8. Capacitance vs. Drain to Source Voltage

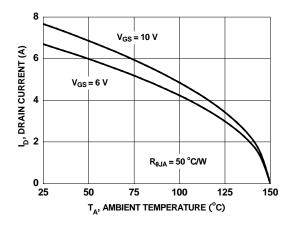


Figure 10. Maximum Continuous Drain Current vs. Ambient Temperature

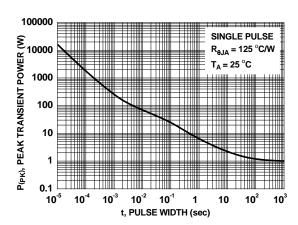


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25$ °C unless otherwise noted.

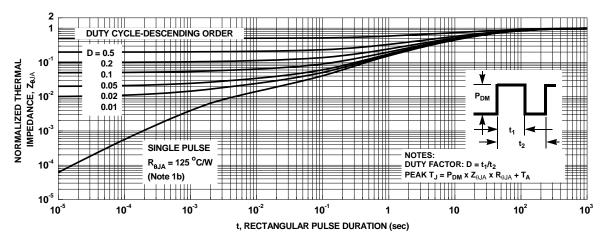
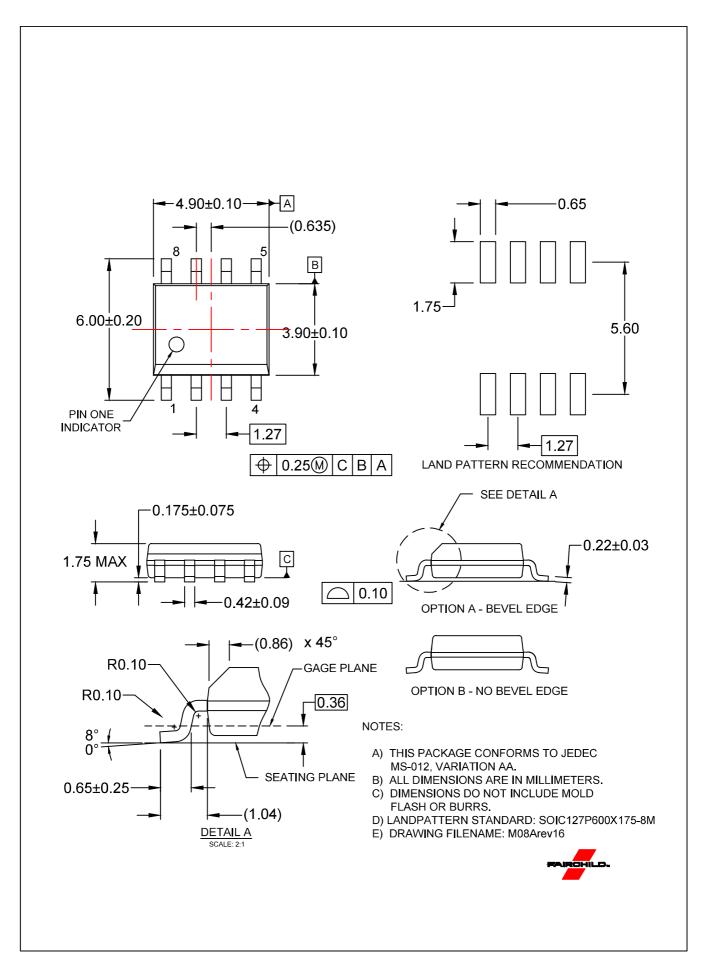


Figure 13. Junction-to-Ambient Transient Thermal Response Curve



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